



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC027N04LS G		<b>Issued</b>		19. January 2018	
<b>MA#</b>				MA001505922					
<b>Package</b>				PG-TDSON-8-39		<b>Weight*</b>		120.46 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.391	1.99	1.99	19851	19851	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		314		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94		
	non noble metal	copper	7440-50-8	37.762	31.33	31.37	313492	313900	
wire	non noble metal	copper	7440-50-8	0.042	0.03	0.03	345	345	
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		691		
	plastics	epoxy resin	-	6.578	5.46		54608		
	inorganic material	silicondioxide	60676-86-0	34.971	29.03	34.56	290323	345622	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.21	1.21	12051	12051	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1374	1374	
solder	noble metal	silver	7440-22-4	0.057	0.05		472		
	non noble metal	tin	7440-31-5	0.046	0.04		378		
	non noble metal	lead	7439-92-1	2.173	1.80	1.89	18040	18890	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		94		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.40	9.41	93978	94100	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		185		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	noble metal	silver	7440-22-4	1.032	0.86		8564		
	non noble metal	copper	7440-50-8	22.292	18.51	19.40	185062	193867	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com